

# **Data sheet**

# SAW duplexer LTE band 28a

Series/type: B8538

Ordering code: B39771B8538P810

Date: October 24, 2018

Version: 2.6

DCN: 80-PA243-19 Rev. A

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RF360 Europe GmbH
A Qualcomm – TDK Joint Venture

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Please read **Cautions and warnings** and **Important notes** at the end of this document.

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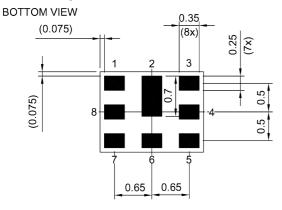
# 1 Application

- Low-loss SAW duplexer for mobile telephone LTE Band 28 systems
- Low insertion attenuation
- Companion type is B8539/B8541 for upper Band 29(Block B)
- Usable pass band 30 MHz
- Duplexer for lower part of Band 28

#### 2 Features

- Package size 1.8±0.1 mm × 1.4±0.1 mm
- Package height 0.475 mm (max.)
- Approximate weight 4 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

## 3 Package



# 4 Pin configuration

1 RX

■ 3 TX

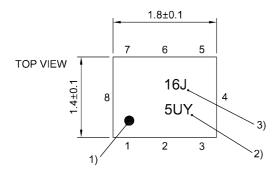
■ 6 ANT

**2**, 4, 5, 7, Ground 8

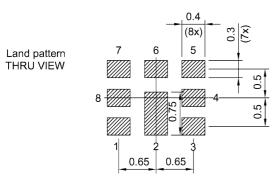
Pad and pitch tolerance ±0.05

SIDE VIEW





- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number



Landing pad tolerance -0.02

**Figure 1:** Drawing of package with package height A = 0.475 mm (max.). See Sec. Package information (p. 22).

# 5 Matching circuit

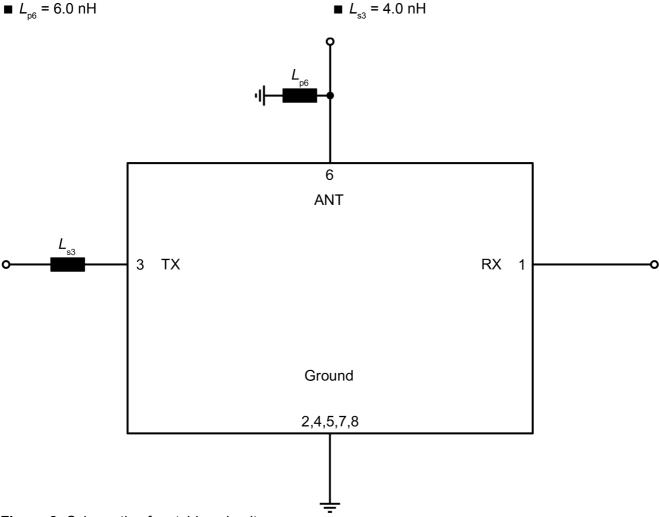


Figure 2: Schematic of matching circuit.

External shunt inductor for ESD protection is recommended at any ports towards antenna.



#### 6 **Characteristics**

#### TX - ANT 6.1

Temperature range for specification = -20 °C ... +90 °C  $T_{\text{SPEC}}$ TX terminating impedance = 50  $\Omega$  with ser. 4.0 nH<sup>1)</sup>  $Z_{\scriptscriptstyle{\mathsf{ANT}}}$ ANT terminating impedance = 50  $\Omega$  with par. 6.0 nH<sup>1)</sup>

RX terminating impedance  $= 50 \Omega$ 

Characteristics TX – ANT				$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	<b>typ.</b> @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{\tiny SPEC}} \end{array}$	
Center frequency			f <sub>C</sub>	_	718	_	MHz
Maximum insertion attenuation			$\alpha_{\text{max}}$				
	703.24 732.76	MHz	max	_	1.8	3.0	dB
Amplitude ripple (p-p)			Δα				
	703.24 732.76	MHz		_	1.0	2.1	dB
Maximum VSWR			$VSWR_{max}$				
@ TX port	703 733	MHz	max	_	1.7	2.0	
@ ANT port	703 733	MHz		_	1.5	2.0	
Minimum attenuation			$\boldsymbol{\alpha}_{\text{min}}$				
	10 670	MHz		30	38	_	dB
	670 694	MHz		30	38	_	dB
	694 695	MHz		30	38	_	dB
	695 698	MHz		<b>7</b> <sup>2)</sup>	26	_	dB
	695 698	MHz		5	26	_	dB
	758.24 787.76	MHz		43	49	_	dB
	788 803	MHz		30	39	_	dB
	859 894	MHz		30	35	_	dB
	1225 1250	MHz		35	45	_	dB
	1406 1466	MHz		35	40	_	dB
	1559 1563	MHz		35	38	_	dB
	1565.42 1573.374	MHz		35	38	_	dB
	1573.374 1577.466	MHz		35	38	_	dB
	1577.466 1585.42	MHz		35	38	_	dB
	1597.55 1605.89	MHz		34	38	_	dB
	1805 1880	MHz		30	36	_	dB
	1930 1995	MHz		30	35	_	dB
	2010 2025	MHz		30	35	_	dB
	2109 2199	MHz		30	34	_	dB
	2400 2484	MHz		28	34	_	dB
	2570 2620	MHz		28	33	_	dB
	2812 2932	MHz		15	32	_	dB
	4900 5950	MHz		15	22	_	dB

See Sec. Matching circuit (p. 6).

Valid for temperature  $T = +15 \,^{\circ}\text{C...} + 70 \,^{\circ}\text{C.}$ 



#### 6.2 ANT - RX

Temperature range for specification  $T_{\scriptscriptstyle{\mathrm{SPEC}}}$ = -20 °C ... +90 °C TX terminating impedance = 50  $\Omega$  with ser. 4.0 nH<sup>1)</sup> ANT terminating impedance = 50  $\Omega$  with par. 6.0 nH<sup>1)</sup>

RX terminating impedance = 50 Ω

Characteristics ANT – RX				$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	<b>typ.</b> @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
Center frequency			f <sub>C</sub>	_	773	_	MHz
Maximum insertion attenuation			$\boldsymbol{\alpha}_{\text{max}}$				
	758.24 787.76	MHz		_	2.3	3.0	dB
Amplitude ripple (p-p)			Δα				
	758.24 787.76	MHz		_	0.9	1.5	dB
Maximum VSWR			$VSWR_{max}$				
@ ANT port	758 788	MHz		_	1.5	2.02)	
	758 788	MHz		_	1.5	2.23)	
@ RX port	758 788	MHz		_	1.8	2.1	
Minimum attenuation			$\boldsymbol{\alpha}_{_{min}}$				
	1.0 699	MHz		40	62	_	dB
	45 65	MHz		50	70	_	dB
	703.24 732.76	MHz		50	65	_	dB
	733.24 747.76	MHz		30	42	_	dB
	814 3000	MHz		40	44	_	dB
	3000 6000	MHz		26	37	_	dB

<sup>1)</sup> See Sec. Matching circuit (p. 6).

<sup>2)</sup> 

Valid for temperature  $T = 0 \,^{\circ}\text{C...} + 90 \,^{\circ}\text{C.}$ Valid for temperature  $T = -20 \,^{\circ}\text{C...} 0 \,^{\circ}\text{C.}$ 



#### 6.3 TX - RX

Temperature range for specification = -20 °C ... +90 °C  $T_{\scriptscriptstyle\mathrm{SPEC}}$ TX terminating impedance = 50  $\Omega$  with ser. 4.0 nH<sup>1)</sup> ANT terminating impedance = 50  $\Omega$  with par. 6.0 nH<sup>1)</sup>

RX terminating impedance = 50 Ω

Characteristics TX - RX			min.	typ.	max.	
			for $T_{\text{SPEC}}$	@ +25 °C	for $T_{\text{SPEC}}$	
Minimum isolation		$\alpha_{mir}$				
	703.24 732.76	MHz	60	63	_	dB
	758.24 787.76	MHz	54 <sup>2)</sup>	57	_	dB
	758.24 787.76	MHz	53 <sup>3)</sup>	57	_	dB

<sup>1)</sup> 

See Sec. Matching circuit (p. 6). Valid for temperature  $T = +20 \,^{\circ}\text{C...} +90 \,^{\circ}\text{C}$ . 2)

Valid for temperature  $T = -20 \, ^{\circ}\text{C...} + 20 \, ^{\circ}\text{C.}$ 



# 7 Maximum ratings

Storage temperature	T <sub>STG</sub> <sup>2)</sup> = -40 °C +85 °C <sup>1)</sup>	
DC voltage	$ V_{DC}  = 5.0 \text{ V (max.)}$	
ESD voltage	V <sub>ESD</sub>	
	100 V (max.) <sup>3)</sup>	
	300 V (max.) <sup>4)</sup>	
	600 V (max.) <sup>5)</sup>	
Input power	P <sub>IN</sub>	
@ TX port: 703 733 MHz	29.5 dBm	LTE 5MHz for 2000h @50C.
@ TX port: other frequency ranges	10 dBm	

<sup>1)</sup> Extended upper limit :168h@125 C .to IEC 60068-2-2Bb.

Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

<sup>&</sup>lt;sup>3)</sup> According to JESD22-A115B (machine model), 10 negative and 10 positive pulses.

Acc to JESD22-A114F (human body model), 10 negative and 10 positive pulses.

<sup>&</sup>lt;sup>5)</sup> According to JESD22-A101C (Charger device model), 3 negative and 3 positive pulses.

#### 8 Transmission coefficients

# 8.1 TX - ANT 0.0 1.0 / √.599 2.0 1.92 3.0 4.0 5.0 710 720 730 740 700 f/MHz0.0 20.0 40.0 60.0 80.0 700 800 675 725 750 825 850 650 775 f/MHz 0.0 Ш 20.0 40.0 60.0 80.0 1000 2000 3000 4000 5000 6000 **f**/MHz -

Figure 3: Attenuation TX – ANT.

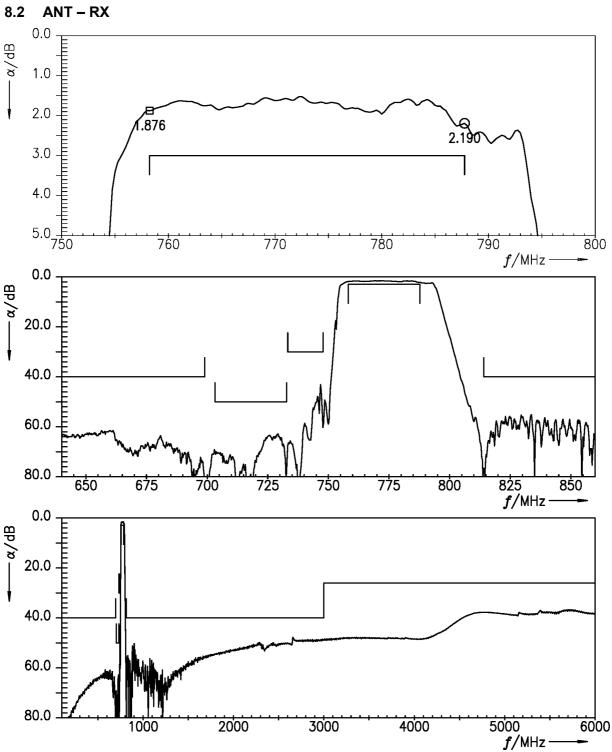


Figure 4: Attenuation ANT – RX.

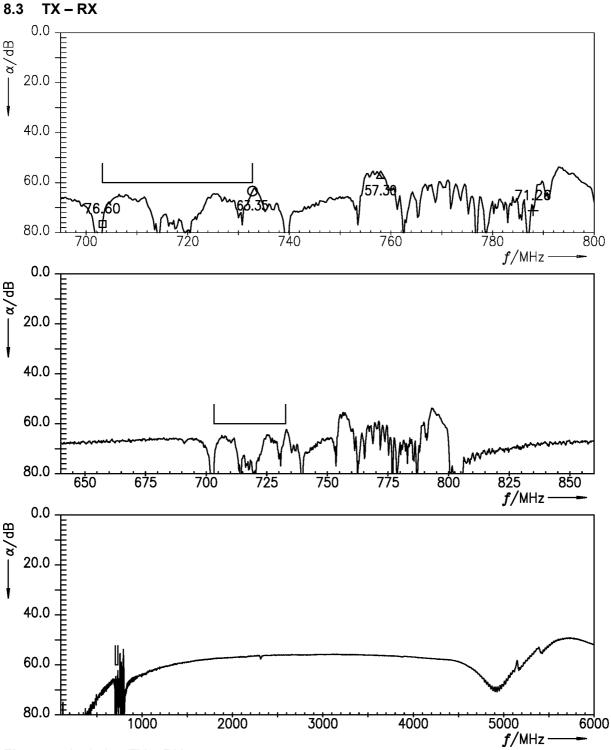
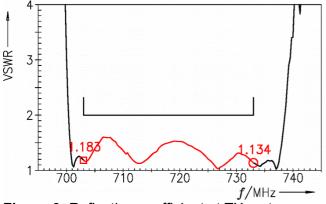


Figure 5: Isolation TX – RX.

#### 9 Reflection coefficients



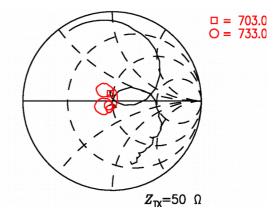
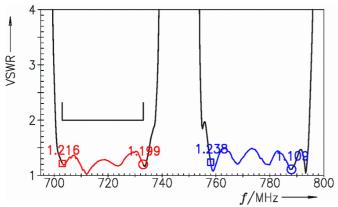


Figure 6: Reflection coefficient at TX port.



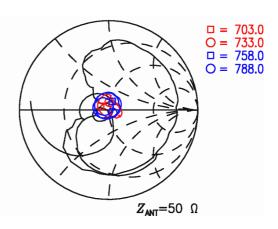
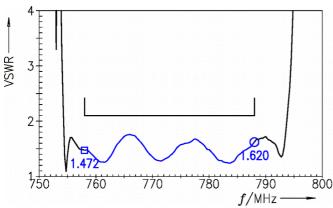


Figure 7: Reflection coefficient at ANT port.



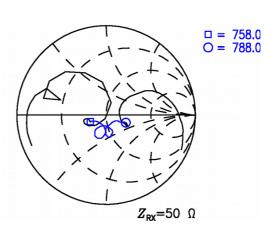
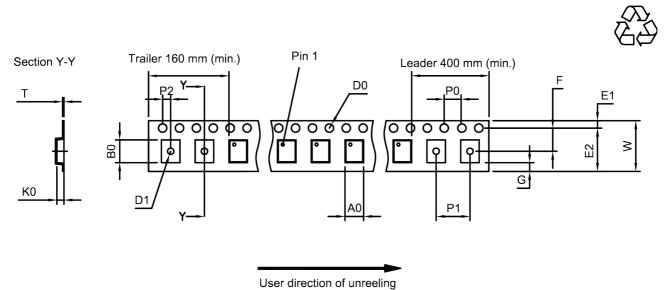


Figure 8: Reflection coefficient at RX port.

# 10 Packing material

## 10.1 Tape



**Figure 9:** Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

$A_0$	1.62±0.05 mm	E <sub>2</sub>	6.25 mm (min.)	P <sub>1</sub>	4.0±0.1 mm
B <sub>0</sub>	2.04±0.05 mm	F	3.5±0.05 mm	P <sub>2</sub>	2.0±0.05 mm
D <sub>0</sub>	1.5+0.1/-0 mm	G	0.75 mm (min.)	Т	0.25±0.05 mm
D <sub>1</sub>	0.8±0.05 mm	$K_0$	0.62±0.05 mm	W	8.0±0.1 mm
E <sub>1</sub>	1.75±0.1 mm	P <sub>0</sub>	4.0±0.1 mm		

Table 1: Tape dimensions.

#### 10.2 Reel with diameter of 180 mm

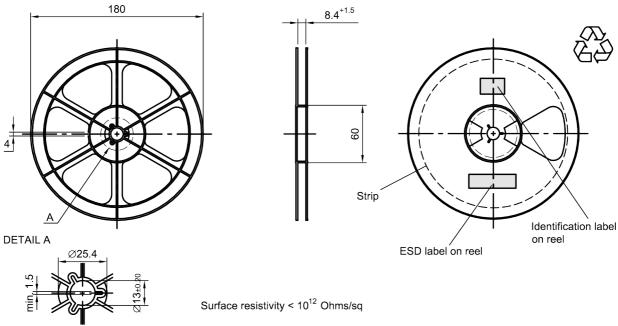


Figure 10: Drawing of reel (first-angle projection) with diameter of 180 mm.

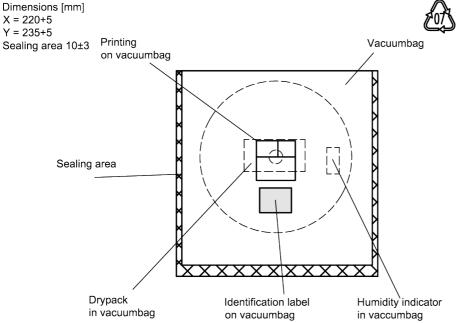


Figure 11: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

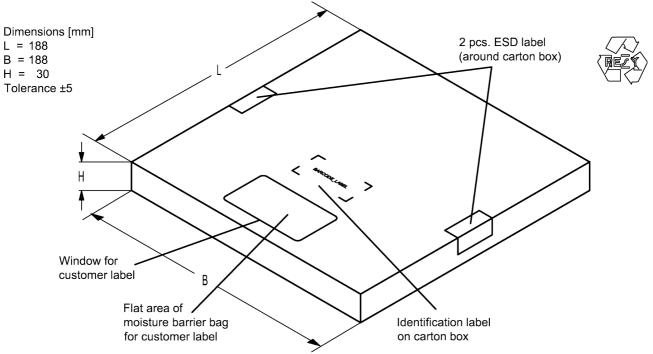
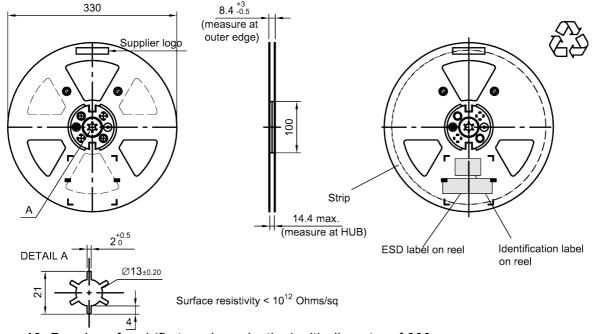


Figure 12: Drawing of folding box for reel with diameter of 180 mm.

#### 10.3 Reel with diameter of 330 mm



**Figure 13:** Drawing of reel (first-angle projection) with diameter of 330 mm.

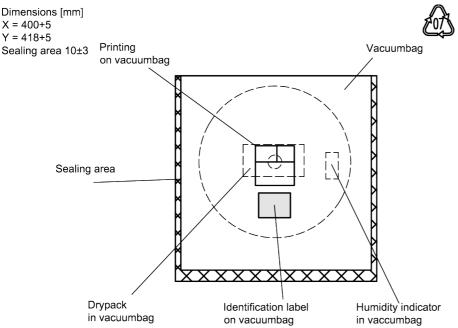


Figure 14: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

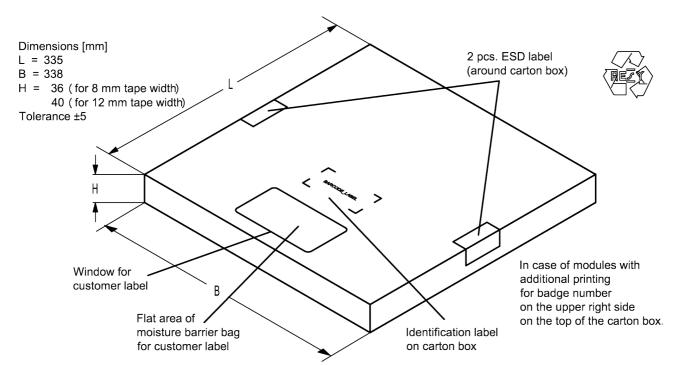


Figure 15: Drawing of folding box for reel with diameter of 330 mm.



### 11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

#### ■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx, is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.

16J => 1234 1 x  $32^2$  + 6 x  $32^1$  + 18 (=J) x  $32^0$  = 1234

The BASE32 code for product type B8538 is 8AT.

#### ■ Lot number:

The last 5 digits of the lot number, e.g., are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.

5UY => 12345  $5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0 =$  12345

Adopted BASE32 code for type number				
Decimal	Base32	Decimal	Base32	
value	code	value	code	
0	0	16	G	
1	1	17	Н	
2	2	18	J	
3	3	19	K	
4	4	20	M	
5	5	21	N	
6	6	22	Р	
7	7	23	Q	
8	8	24	R	
9	9	25	S	
10	Α	26	Т	
11	В	27	V	
12	С	28	W	
13	D	29	Х	
14	E	30	Y	
15	F	31	Z	

Adopted BASE47 code for lot number				
Decimal	Base47	Decimal	Base47	
value	code	value	code	
0	0	24	R	
1	1	25	S	
2	2	26	Т	
3	3	27	U	
4	4	28	V	
5	5	29	W	
6	6	30	Х	
7	7	31	Y	
8	8	32	Z	
9	9	33	b	
10	Α	34	d	
11	В	35	f	
12	С	36	h	
13	D	37	n	
14	E	38	r	
15	F	39	t	
16	G	40	V	
17	Н	41	\	
18	J	42	?	
19	K	43	{	
20	L	44	}	
21	М	45	<	
22	N	46	>	
23	Р			

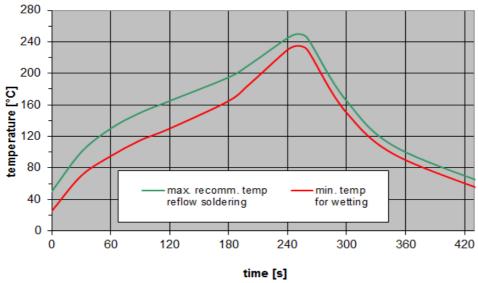
**Table 2:** Lists for encoding and decoding of marking.

# 12 Soldering profile

The recommended soldering process is in accordance with IEC  $60068-2-58-3^{rd}$  edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
<i>T</i> > 230 °C	min. 10 s
T > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	-
peak temperature T <sub>peak</sub>	250 °C +0/-5 °C
wetting temperature $T_{min}$	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

**Table 3:** Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).



**Figure 16:** Recommended reflow profile for convection and infrared soldering – lead-free solder.

#### 13 Annotations

## 13.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

#### 13.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

# 13.3 Ordering codes and packing units

Ordering code	Packing unit
B39771B8538P810	15000 pcs
B39771B8538P810S 5	5000 pcs

Table 4: Ordering codes and packing units.

### 14 Cautions and warnings

## 14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <a href="https://www.rf360jv.com/orderingcodes">www.rf360jv.com/orderingcodes</a>.

#### 14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

#### 14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

#### 14.4 Package information

## Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

#### **Dimensions**

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

#### **Projection method**

Unless otherwise specified first-angle projection is applied.



#### 15 Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
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